

ULTRA-FINE PITCH SOCKET & HEADER

SS4 Mates with:

ST4

ST4 Mates with:

SS4

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SS4 or www.samtec.com?ST4

Insulator Material:

Black LCP

Contact Material:

Phosphor Bronze

Plating:

Au or Sn over

50 μ" (1.27 μm) Ni

Current Rating:

1.6 A per pin

(2 pins powered)

Operating Temp Range:

-55 °C to +125 °C

RoHS Compliant:

Yes

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max

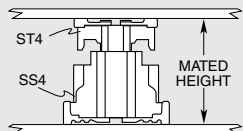
RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594

MATED HEIGHT

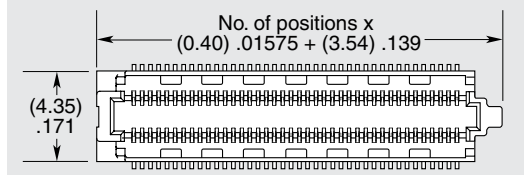


MATED HEIGHT*		
ST4 LEAD STYLE	SS4 LEAD STYLE	
	-3.00	-3.50
-1.00	(4.00) .157	(4.50) .177
-1.50	(4.50) .177	(5.00) .197
-2.50	(5.50) .217	(6.00) .236

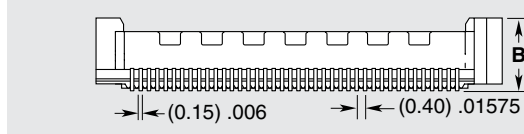
*Processing conditions will affect mated height.

Note: Some lengths, styles and options are non-standard, non-returnable.

SS4	POSITIONS PER ROW	LEAD STYLE	PLATING OPTION	D	K	TR
	-10, -20, -30, -40, -50	-3.00 = 3.00 mm -3.50 = 3.50 mm	-L = 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail		(Required in callout) -K = (3.50 mm) .138" DIA Polyimide Film Pick & Place Pad	(Required in callout) -TR = Tape & Reel



LEAD STYLE	A	B
-3.00	(2.85) .112	(3.50) .138
-3.50	(3.35) .132	(4.00) .157



HIGH-SPEED CHANNEL PERFORMANCE

SS4/ST4 @ 4 mm Mated Stack Height

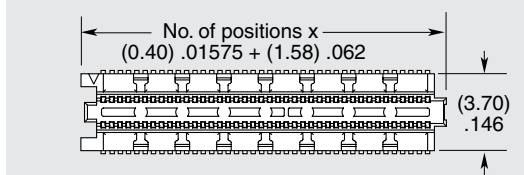
Rating based on Samtec reference channel. For full SI performance data visit www.samtec.com or contact SIG@samtec.com

28
Gbps

POWER/SIGNAL APPLICATION

Compatible with UMPT/UMPS for flexible two-piece power/signal solutions

ST4	POSITIONS PER ROW	LEAD STYLE	PLATING OPTION	D	P	TR
	-10, -20, -30, -40, -50	-1.00 = 1.00 mm -1.50 = 1.50 mm -2.50 = 2.50 mm	-L = 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail		(Required in callout) -P = Pick & Place Pad	(Required in callout) -TR = Tape & Reel



LEAD STYLE	A	B
-1.00	(1.00) .039	(3.08) .121
-1.50	(1.50) .059	(3.58) .141
-2.50	(2.50) .098	(4.58) .180

